

**SPECIAL PROCEDURES SUBMISSION**

PATENT

Docket No. MTI-31607

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Lee, Teck Kheng

Serial No. : 10/050,507

Filing Date : January 16, 2002

For: Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking

Group Art Unit: 2813

Confirmation No.: 7687

Examiner : THOMPSON, Craig

**RECEIVED**

FEB 08 2005

**OFFICE OF PETITIONS**

**CERTIFICATION UNDER 37 CFR 1.8(a) and 1.10**

I hereby certify that, on the date shown below, this correspondence is being hand delivered to OFFICE OF PETITIONS at the US Patent and Trademark Office.

Date: February 8, 2005



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2201 South Clark Place

Crystal Plaza 4, Suite 3C23

Arlington, Virginia 22202

**PETITION UNDER 37 CFR §§ 1.313(c)(2) and 1.114**

Sir:

Applicant hereby petitions **withdrawal** of the above-referenced application from issue pursuant to 37 CFR §§ 1.313(c)(2). A Notice of Issue was received indicating the issue date as **February 22, 2005**, as **US Patent No. 6,858,940**.

This petition is being made to permit reopening of prosecution for the Examiner to consider references that were cited in a related application but not cited in the present application. Applicant submits herewith a Request for Continued Examination in compliance with § 1.114.

Please charge the Petition fee set forth in 37 CFR § 1.17(h) and the RCE fee set forth in 37 CFR § 1.17(e) to deposit account No. 23-2053. The Applicant is a large entity.

The consideration and grant of this petition is earnestly requested.

Respectfully submitted,



Kristine M. Strodthoff, Reg. No. 34,259

Dated: February 7, 2005

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Attachments:

Request for Continued Examination

Supplemental Information Disclosure Statement

Form 1449/PTO

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